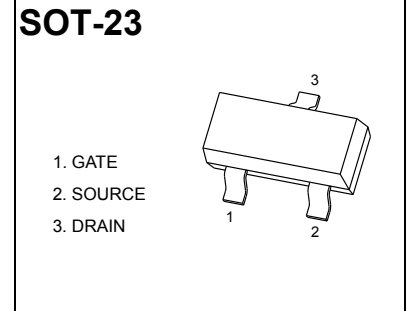


SOT-23 Plastic-Encapsulate MOSFETS

30V N-Channel Enhancement Mode Field Effect Transistor

$V_{(BR)DSS}$	$R_{DS(on)}$ Typ	I_D
30V	27mΩ @ 4.5V	5.8A
	29mΩ @ 3.3V	



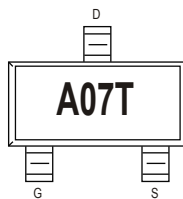
FEATURE

High dense cell design for extremely low RDS(ON)
Exceptional on-resistance and maximum DC current capability

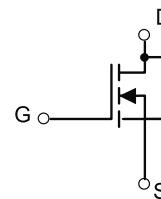
APPLICATION

- Load Switch for Portable Devices
- DC/DC Converter

MARKING



Equivalent circuit



PACKAGE SPECIFICATIONS

Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (pcs)	Box Size (mm)	QTY/Box (pcs)	Carton Size (mm)	Q'TY/Carton (pcs)
SOT-23	7'	330	3000	203×203×195	45000	438×438×220	180000

MAXIMUM RATINGS ($T_a=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	30	V
Gate-Source Voltage	V_{GS}	±12	
Continuous Drain Current	I_D	5.8	A
		4.6	
Maximum Power Dissipation ²⁾	P_D	1.5	W
		0.9	
Pulsed Drain Current ¹⁾	I_{DM}	23	A
Operating Junction and Storage Temperature Range	T_J	150	°C
Storage Temperature Range	T_{stg}	-50 to 150	°C
Thermal Resistance Junction-Ambient	$R_{\theta JA}$	100	°C/W

Notes

- 1) Pulse width limited by maximum junction temperature.
2) Surface Mounted on FR4 Board, $t \leq 5$ sec.
3) The above data are for reference only.



MOSFET ELECTRICAL CHARACTERISTICS

$T_a=25^{\circ}\text{C}$ unless otherwise specified

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Off Characteristics						
Drain-source breakdown voltage	V _{(BR) DSS}	V _{GS} = 0V, I _D =250uA	30			V
Zero gate voltage drain current	I _{DSS}	V _{DS} =24V,V _{GS} = 0V			1	uA
	I _{DSS}	V _{DS} =24V,V _{GS} = 0V,T _j =125 C			100	uA
Gate-source leakage current	I _{GSS}	V _{GS} =±12V, V _{DS} = 0V			±100	nA
On characteristics						
Drain-source on-resistance (note 3)	R _{DS(on)}	V _{GS} =4.5V, I _D =5.8A		27	32	mΩ
		V _{GS} =3.3V, I _D =4A		29	45	mΩ
		V _{GS} =2.5V, I _D =2A		35	50	mΩ
Forward tranconductance	g _{FS}	V _{DS} =5V, I _D =5A	8			S
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250uA	0.5	0.8	1.2	V
Dynamic Characteristics (note 4)						
Input capacitance	C _{iss}	V _{DS} =15V,V _{GS} =0V,f =1MHz		635		pF
Output capacitance	C _{oss}			135		pF
Reverse transfer capacitance	C _{rss}			40		pF
Total Gate Charge	Q _g	V _{DS} =15V I _D =5A, V _{GS} =4.5V		10.5		nC
Gate Source Charge	Q _{gs}			1.6		nC
Gate Drain Charge	Q _{gd}			2.7		nC
Switching Characteristics (note 4)						
Turn-on delay time	t _{d(on)}	V _{DD} =15V, I _D =5A, R _G =3.3Ω, V _{GS} =4.5V		7.5		ns
Turn-on rise time	t _r			18		ns
Turn-off delay time	t _{d(off)}			36		ns
Turn-off fall time	t _f			5		ns
Drain-source diode characteristics and maximum ratings						
Source drain current(Body Diode)	I _{SD}	T _A =25℃			1.5	A
Diode forward voltage (note 3)	V _{SD}	I _S =3A,V _{GS} =0V		0.82	1.2	V

Note :

1. Repetitive Rating : Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 5$ sec.
3. Pulse Test : Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production testing.

Typical Characteristics

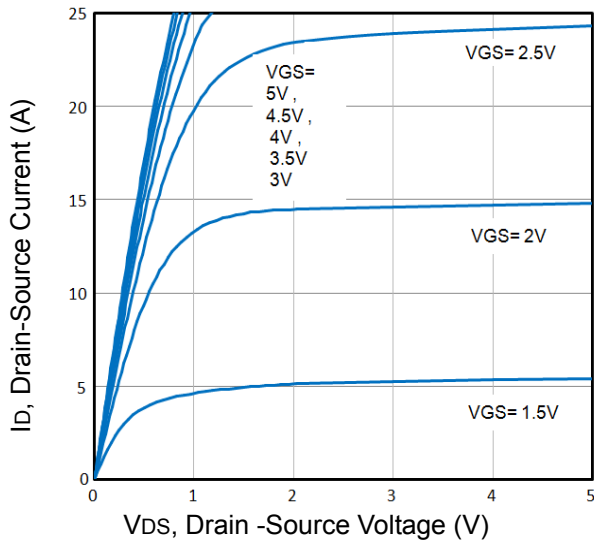


Fig1. Typical Output Characteristics

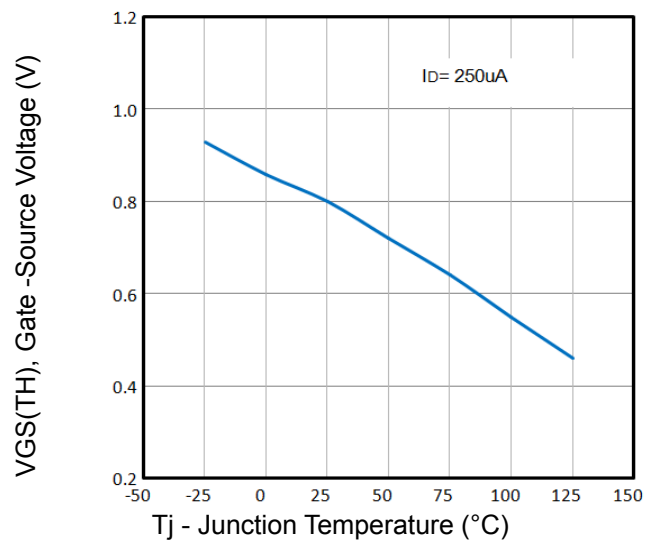


Fig2. Normalized Threshold Voltage Vs. Temperature

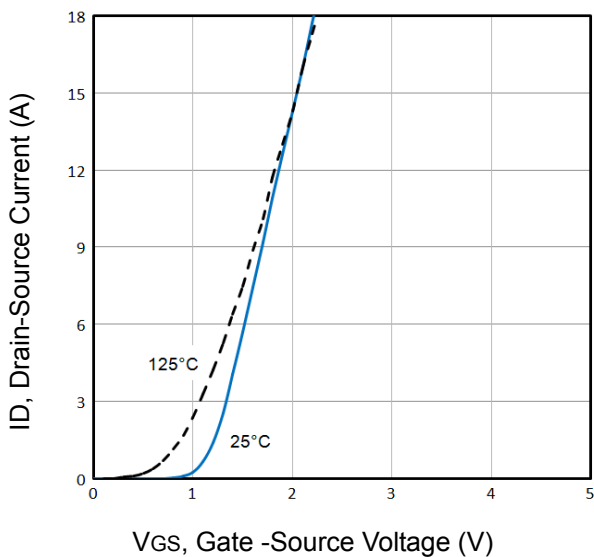


Fig3. Typical Transfer Characteristics

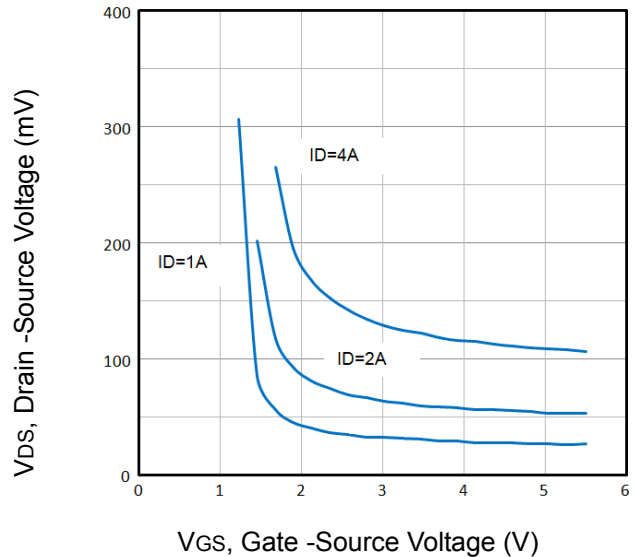


Fig4. Drain-Source Voltage vs Gate-Source Voltage

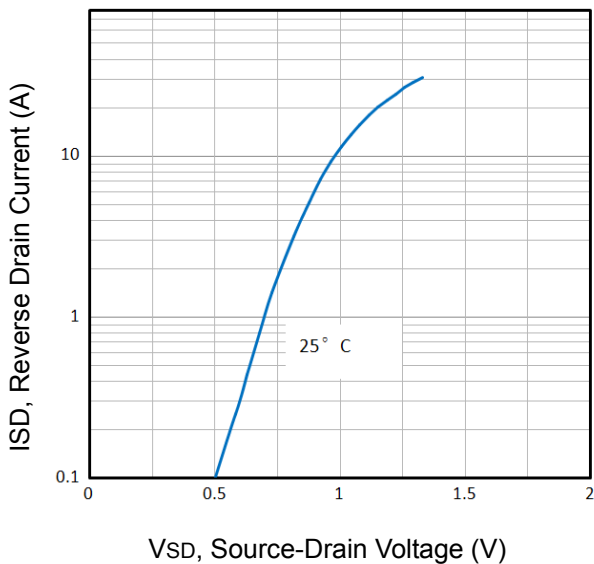


Fig5. Typical Source-Drain Diode Forward Voltage

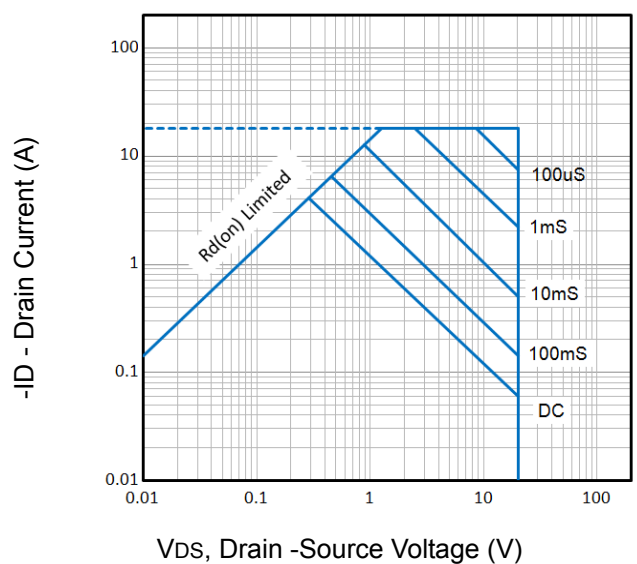


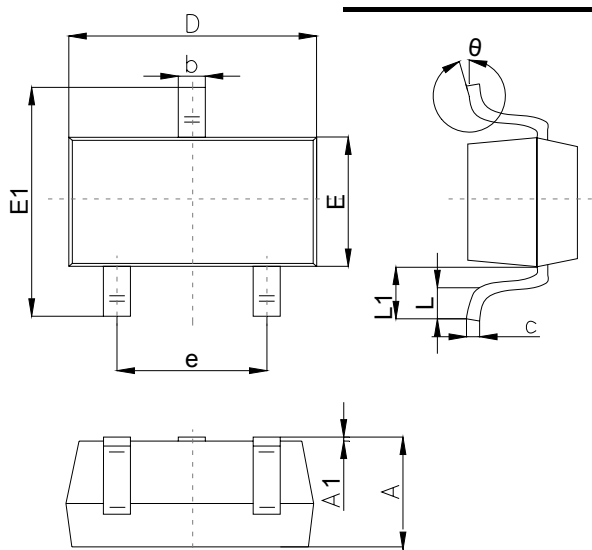
Fig6. Maximum Safe Operating Area

The curve above is for reference only.

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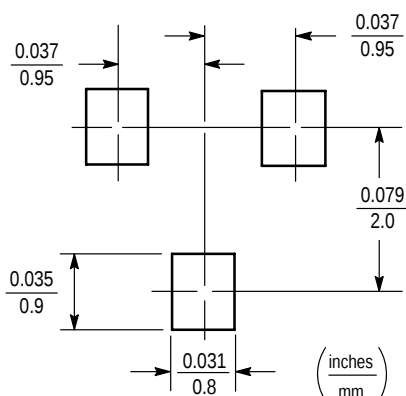
Outlitne Drawing

SOT-23 Package Outline Dimensions



Symbol	Dimensions In Millimeters		
	Min	Typ	Max
A	0.90		1.40
A1	0.00		0.10
b	0.30		0.50
c	0.08		0.20
D	2.80	2.90	3.10
E	1.20		1.60
E1	2.25		2.80
e	1.80	1.90	2.00
L	0.10		0.50
L1	0.4		0.55
θ	0°		10°

Suggested Pad Layout



Note:

1. Controlling dimension: in/millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.